

Abstract

A dressing apparatus DA is constructed from a pad holding mechanism 10 which holds a polishing pad 15 that has a doughnut disk-form pad surface 15a, and which causes this polishing pad 15 to rotate, a dressing tool 2 which has a substantially rectangular dressing surface 3, and a dressing tool holding mechanism 1 which holds the dressing tool 2 so that the dressing surface 3 of this dressing tool 2 is caused to face the pad surface 15a of the polishing pad 15 that is held and caused to rotate by the pad holding mechanism 10. The dressing tool holding mechanism 1 causes the held dressing tool 2 to contact the pad surface 15a in a state in which the centerline L1 in the direction of width of the dressing surface 3 is oriented so that this centerline extends in the radial direction of the pad surface 15a, and thus causes dressing to be performed. As a result, the flatness of the working surface following dressing can be improved.